IN THE SPECIFICATION

Please replace the paragraph at page 1, lines 10-17 with the following amended paragraph:

Because the perspectives of wafer factories are good and their throughputs expand continually, there is an abrupt increase in the equipment quantities and the degree of machine automation. However, the required training of technicians becomes more cumbersome, and it is difficult to reckon with machine anomalies occurring seldom such as wafer fragmentation or malfunction by long-term in-situ monitoring. Therefore, although the CMP (chemical mechanic polishing) Ebara machine has good stability, the problems of wafer fragmentation and wafer dropping due to unknown reasons may still occur.

Please replace the section at page 2, lines 15-24 with the following amended section:

Fig. 1 is a diagram showing the actual hardware connection of the present invention;

Fig. 2 is a flowchart of a smart automatic recording method for monitoring wafer fragmentation according to an embodiment of the present invention;

Fig. 3 shows the process to capture, merge, and store the images of wafers; and,

Fig. 4 shows the process performed by means of IC (integrated circuit) design and a control card to capture, merge, and store the image of wafers[[;]]

~~Fig. 5 is a flowchart of an automatic monitoring system for burglarproof purpose of house derived and modified from the present invention~~.

Please replace the paragraph at page 3, lines 2-15 with the following amended paragraph:

As shown in Fig. 1, a smart recording system for monitoring wafer fragmentation according to a preferred embodiment of the present invention comprises a plurality of photographing devices 11 such as CCD (charge coupled device) cameras or general recorders so that the circumstances can be monitored when wafers are polished. The photographed images are then transferred to a multiple-image receiver 13 by a multiple-image transmitter 12. The photographed images are digitized and recorded simultaneously by a plurality of photographing devices. After the multiple-image receiver 13 receives the image signals, the images captured at the same time will be merged into the same image frame 14 by the multiple-image receiver 13. Next, the multiple-image receiver 13 transfers

the image signals to the input terminal of an image-capturing card in a PC. The PC also receives the wafer-entry and wafer-exit signals and the signal of wafer fragmentation transferred from the I/O (input/output) port of a polishing apparatus. A whole monitoring system is thus formed.

Please delete the paragraph at page 5, lines 16-20.